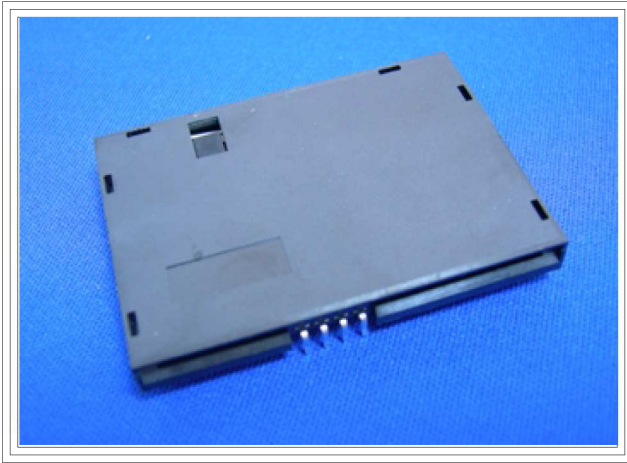


Smart (IC) Card Connector

Landing (H:5.8mm) DIP Type

ISO14001 QC080000 ISO14001 QC080000 ISO14001 QC080000 ISO14001 QC080000 ISO14001 QC080000 ISO14001



Part No:

SMCRB-20830B900-G

1. GENERAL CHARACTERISTICS.

DIMENSIONS: 55.50L * 40.00W * 5.80H mm.

WEIGHT: APPROX. 12.5g

CONTACT PRINCIPLE: LANDING TECHNOLOGY.

OPERATING POSITION: SHAFT UP / DOWN / HORIZONTAL.

MOUNTING SYSTEM: THRU-HOLE WITH SNAP-IN-LOCK

DURABILITY: 300,000 CYCLES MIN.

2. MECHANICAL CHARACTERISTICS

INSULATION MATERIAL: THERMOPLASTIC, UL94V-0

3. ELECTRICAL CHARACTERISTICS.

NUMBER OF CONTACT : 8 PINS

CONTACT RESISTANCE: 50mΩ TYPICAL, 100mΩ MAX.

INSULATION RESISTANCE PIN TO PIN: > 1000MΩ / 500 VDC.

SWITCH TYPE: BLADE

OPERATION: NORMALLY OPEN.

4. SOLDERABILITY.

WAVE: NOT APPLICABLE

IR REFLOW: 230°C, 15SEC. MAX

MANUAL : 360°C 3sec. MAX.

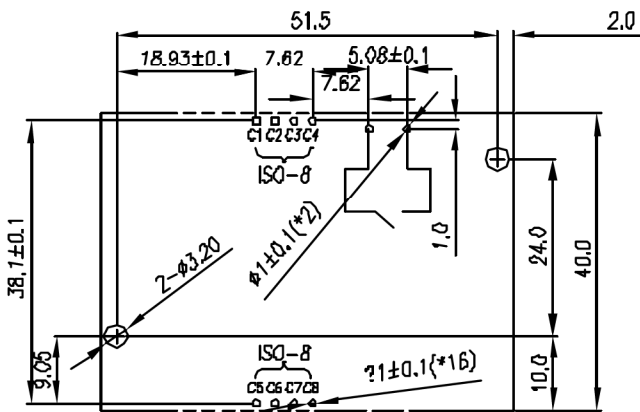
5. ENVIRONMENTAL CHARACTERISTICS.

OPERATING TEMPERATURE: -40°C ~ +85°C

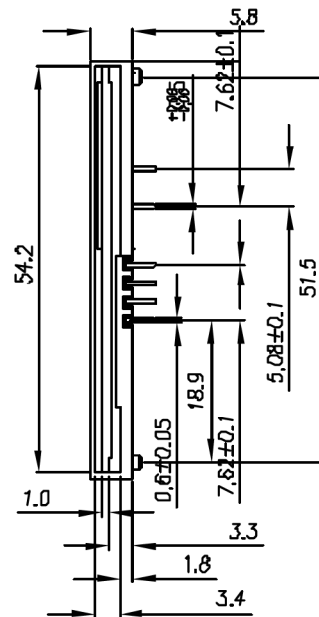
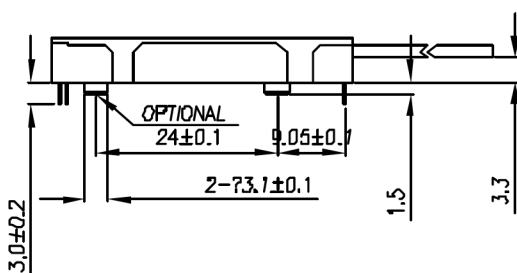
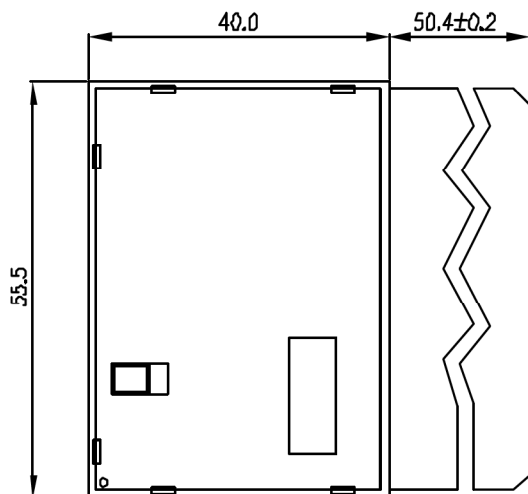
OPERATING HUMIDITY: 10% - 95% RH

STORAGE TEMPERATURE: -40°C ~ +85°C.

STORAGE HUMIDITY: 10% ~ 95% RH



UNIT:mm:TOLERANCES:±0.15mm
REFERENCE DIMENSION FOR PCB LAYOUT



UNIT:mm:TOLERANCES:±0.15mm
MECHANICAL OUTLINE DIMENSION